SDLS004

D2633, JANUARY 1981-REVISED MARCH 1988

- Parallel Register Inputs (15592)
- Parallel 3-State I/O: Register Inputs/ Counter Outputs ('LS593)
- Counter has Direct Overriding Load and Clear
- Accurate Counter Frequency: DC to 20 MHz

description

The 'LS592 comes in a 16-pin package and consists of a parallel input, 8-bit storage register feeding an 8-bit binary counter. Both the register and the counter have individual positive-edge-triggered clocks. In addition, the counter has direct load and clear functions. A low-going RCO pulse will be obtained when the counter reaches the hex word FF. Expansion is easily accomplished for two stages by connecting RCO of the first stage to CCKEN of the second stage. Cascading for larger count chains can be accomplished by connecting RCO of each stage to CCK of the following stage.

The 'LS593 comes in a 20-pin package and has all the features of the 'LS592 plus 3-state I/O, which provides parallel counter outputs. The tables below show the operation of the enable (CCKEN, CCKEN) inputs. A register clock enable (RCKEN) is also provided.

OUTPUT ENABLE CONTROL ('593 ONLY)

	G	G	A/Q _A thru H/Q _H
İ	L	L	input mode
	L	H	input mode
	Н	L	output mode
	Н	н	input mode

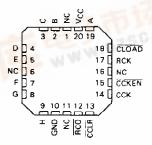
COUNTER CLOCK ENABLE CONTROL

CCKEN	CCKEN	EFFECT ON CCK
Ł	L	Enable
L	Н	Disable
н	L	Enable
н	н	Enabl e

SN54LS592 . . . J OR W PACKAGE SN74LS592 . . . N PACKAGE (TOP VIEW)

B [1	U16	Vcc
C Z	15] A
□ [] 3	14	CLOAD
E [4	13	RCK
F 🗌 5	12	CCKEN
G []6	11	ССК
Н 🛮 7	10	CCLR
GND 🗆 8	9	RCO

SN54LS592 . . . FK PACKAGE (TOP VIEW)

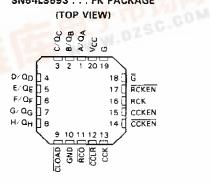


NC - No internal connection

SN54LS593 . . . J OR W PACKAGE SN74LS593 . . . DW OR N PACKAGE SC.COM (TOP VIEW)

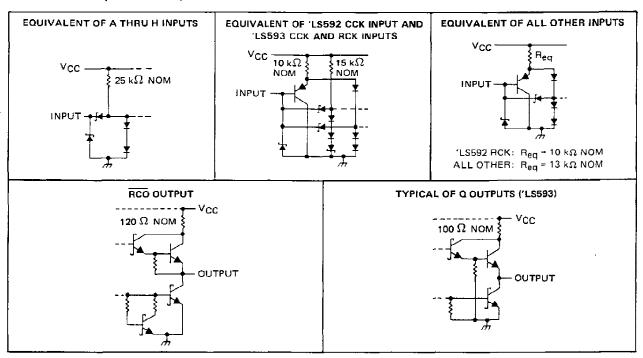
A/QA	1	U20	□ vcc
B/Qg [2	19	G
C/QC	3	18	□ē
ם מם עם	4	17	RCKEN
E/QE [5	16	RCK
F/QF	6	15	CCKEN
G/QG 🗌	7	14	CCKEN
нион 🗌	8	13	CCK
CLOAD [9	12	CCLR
GND 🗌	10	11	RCO

SN54LS593 . . . FK PACKAGE (TOP VIEW)

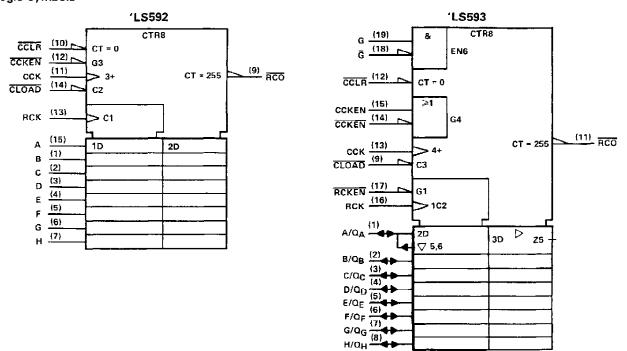


dzsc.com

schematics of inputs and outputs

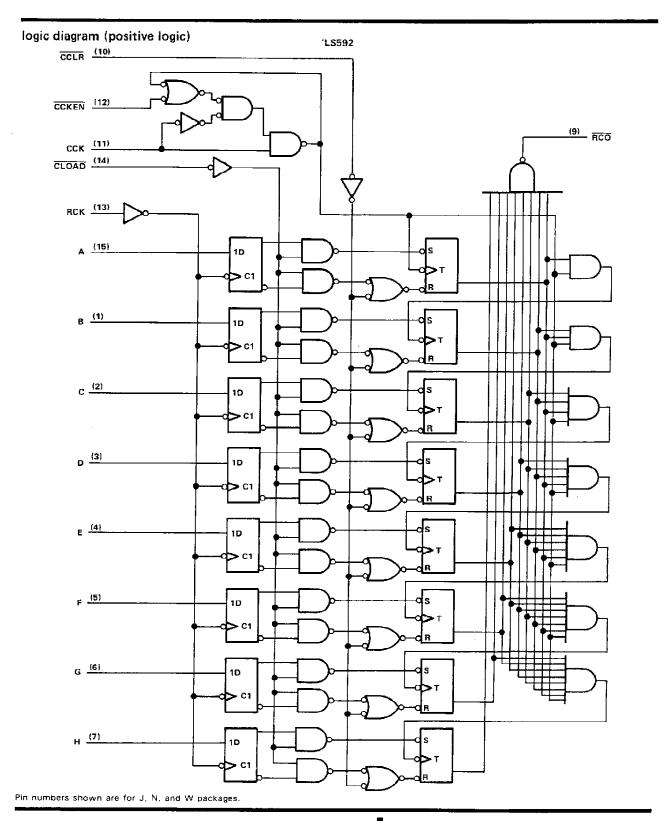


logic symbols†

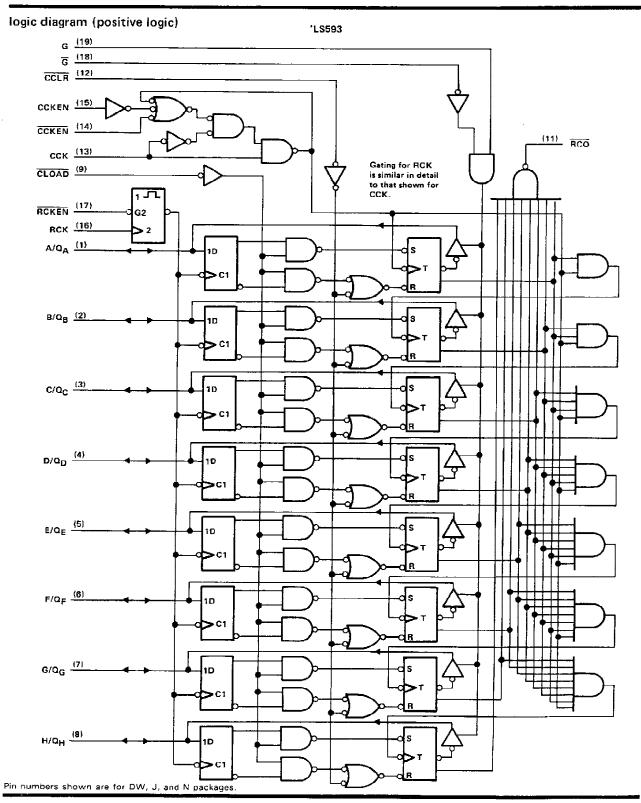


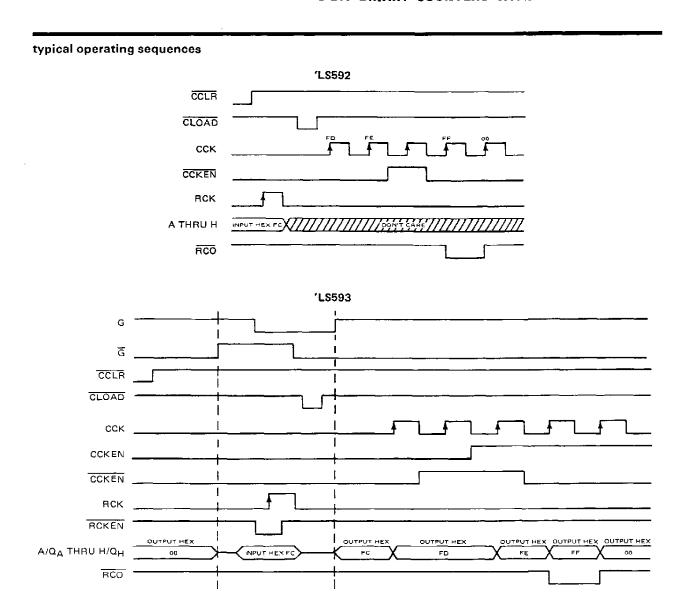
 $^{^\}dagger$ These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for DW, J, N, and W packages.





SN54LS593, SN74LS593 8-BIT BINARY COUNTERS WITH INPUT REGISTERS





absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

oply voltage, VCC (see Note 1)	7 V
out voltage (excluding I/O ports)	7 V
state output voltage (including I/O ports)	.5 V
erating free-air temperature range: SN54LS592, SN54LS593	
SN74LS592, SN74LS593 0°C to 7	O°C
orage temperature range	0°C

NOTE 1: Voltage values are with respect to the network ground terminal.

recommended operating conditions

	-	·	SN54LS'				UNIT		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.7			8.0	· ·
Іон	High-level output current	RCO			– 1			– 1	
'UH		Q 'LS593 only			- 1			- 2.6	mΑ
†OL	Law-level output current	RCO			8			16	
UL	Cove-level output culterit	Q 'L5593 only			12			24	mA
fcck	Counter clock frequency		0		20	0		20	MHz
^t w (CCK)	Duration of counter clock p	ulse	25			25			ns
tw (CCLR)	Duration of counter clear pu	lse	20	•		20	<u>·</u>		ns
tw (RCK)	Duration of register clock po	ılse	20			20			ns
tw (CLOAD	Duration of counter load pu	Ise	40			40			ns
t _{su}	Register enable setup time	RCKEN low to RCK 1 , 'LS593	20			20			ns
	Counter enable setup time	CCKEN low, 'LS592	30			30			
t _{\$u}	before CCK 1	CCKEN low or CCKEN high, 'LS593	30			30			ns
		CCLR inactive before CCK 1	20			20			-
+	Setup time	CLOAD inactive before CCK †	20			20			
^t su	Setup time	RCK † before CLOAD † (see Note 2)	30			30			ns
		Data A thru H before RCK †	20			20			
th	Hold time	Data A thru H after RCK †	0	·		0			
'11		All others	0			0		<u></u>	ns
TA	Operating free-air temperatu	re	- 55		125	0		70	°C

NOTE 2: This time insures the data saved by RCK ↑ will also be loaded into the counter.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS†			SN54LS'			SN74LS'			
					TYP*	MAX	MIN	TYP‡	MAX	UNIT	
Vικ		VCC = MIN. II = -18 m	А	İ		-1.5			- 1.5	٧	
	'LS593 Q	V _{CC} = MIN, V _{IH} = 2 V,	I _{OH} = -1 mA	2.4	3.2						
∨он		V _{II} = MAX	IOH = -2.6 mA	<u> </u>			2.4	3.1		V	
	RCO		I _{OH} = -1 mA	2.4	3.2		2.4	3.2			
i	′LS593 Q		IOL = 12 mA	ļ	0.25	0.4		0.25	0.4		
Voi		$V_{CC} = MIN$, $V_{IH} = 2 V$,						0.35	0.5	V	
102	RCO	VIL = MAX	IOL = 8 mA		0.25	0.4		0.25	0.4		
			I _{OL} = 16 mA					0.35	0.5		
^I OZH	'LS593 Q	$V_{CC} = MAX$, $V_{IH} = 2 V$, $V_{O} - 2.7 V$	V _{IL} = MAX.			20			20	μΑ	
^l OZL	'L\$593 Q	$V_{CC} = MAX, V_{IH} = 2 V,$ $V_{O} = 0.4 V$	V _{IL} = MAX,			-0.4			-0.4	mΑ	
	'LS593 Q		V _I = 5.5 V			0.1			0.1		
11	Others	$V_{CC} = MAX$	VCC = MAX			0.1				mΑ	
¹ін		$V_{CC} = MAX$, $V_I = 2.7 V$				20			20	μА	
·	CCK					-0.8			-0.8		
	'L\$592					-0.2			-0.2		
IL	RCK /LS593	$V_{CC} = MAX$, $V_{I} = 0.4 V$				- O.B			-0.8	mΑ	
	A thru H					-0.4			-0.4		
	Others					-0.2			-0.2		
los [§]	'LS593 Q	V MAY V GV		- 30		- 130	- 30		- 130	mA	
105	RCO	$V_{CC} = MAX, V_0 = 0 V$		- 20		- 100	- 20		- 100	1110	
	'LS592 CCH				40	60		40	60		
	ICCL	V _{CC} = MAX,			40	60		40	60		
Icc	ГССН	All possible inputs grounded,			47	70		47	70	mΑ	
	'LS593 I _{CCL}	All outputs open			53	80		53	80		
	¹ccz				57	85		57	85		

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

 $^{^{\}ddagger}$ All typical values are at V_{CC} = 5 V, T_{A} = 25 °C.

Not more than one output should be shorted at a time and the duration of the short-circuit should not exceed one second.

switching characteristics, $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$, (see note 3)

	FROM	то	TEST CONDITIONS		T	'LS592			'LS593		UNIT
PARAMETER	(INPUT)	(OUTPUT)	TEST COND	ITIONS	MIN	TYP	MAX	MIN	TYP	MAX	CIVIT
†max	ССК	RCO	RL=1kΩ,	$R_L = 1 \text{ k}\Omega$, $C_L = 30 \text{ pF}$		35		20	35		MHz
¹₽LH	CCK1	O.							14	21	ns
tPHL.	CCK t	Q	1						26	39	nş
īРLН	CLOAD +	Q							34	51	ns
tpHL	CLOAD +	Ω							28	42	ns
tPHL	CCLR +	۵	$R_{L} = 667 \Omega$,	Cլ = 45 pF					25	38	ns
tPZH	G t	Q]						31	47	ns
[†] PZL	G t	a	1					<u> </u>	27	40	ns
^t PZH	G↓	a							29	45	ns
tPZL.	G i	a]						31	47	ns
†PHZ	G t	Q.							33	50	ns
tPLZ ·	G +	a	B = 663.0	C - E - E					35	52	ns
tPH2	<u>G</u> ↑	a	RL = 667 Ω,	C[= 5 pr					26	39	ns
^t PLZ	Ğı	Q							28	42	ns
^t PLH	CCK t	RCO				15	23		14	21	пş
^t PHL	CCK 1	RCO				20	30		20	30	ns
^t PLH	CLOAD +	ACO	R _L = 1 kΩ,	$C_L = 30 pF$		31	47		31	47	กร
tPHL.	CLOAD +	RCD				27	41		27	41	ns
^t PLH	CCLR +	RCO				30	45		30	45	ns
tPLH	RCK 1	RCO	R _L = 1 kΩ;	C _L = 30 pF		35	53	L	42	63	ns
^t PHL	RCK †	RCO	CLOAD = L			30	45		33	50	ns

NOTE 3: Load circuits and voltage waveforms are shown in Section 1.

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26-Sep-2005

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-87621012A	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
5962-8762101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
5962-8762101EA	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
5962-8762101FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
5962-8762101FA	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS592J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS592J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SN54LS593J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN54LS593J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SN74LS592D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR
SN74LS592N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS592N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS592N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS592N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS592NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS592NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS592NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS592NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DW	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM



PACKAGE OPTION ADDENDUM

26-Sep-2005

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Packag Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp (3)
SN74LS593DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWR	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593DWRE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS593N	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS593N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS593N3	OBSOLETE	PDIP	N	20		TBD	Call TI	Call TI
SN74LS593NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS593NE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
SN74LS593NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593NSR	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS593NSRE4	ACTIVE	SO	NS	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54LS592FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592J	ACTIVE	CDIP	J	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS592W	ACTIVE	CFP	W	16	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593FK	ACTIVE	LCCC	FK	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593J	ACTIVE	CDIP	J	20	1	TBD	Call TI	Level-NC-NC-NC
SNJ54LS593W	OBSOLETE			20		TBD	Call TI	Call TI
SNJ54LS593W	OBSOLETE			20		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.



PACKAGE OPTION ADDENDUM

26-Sep-2005

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

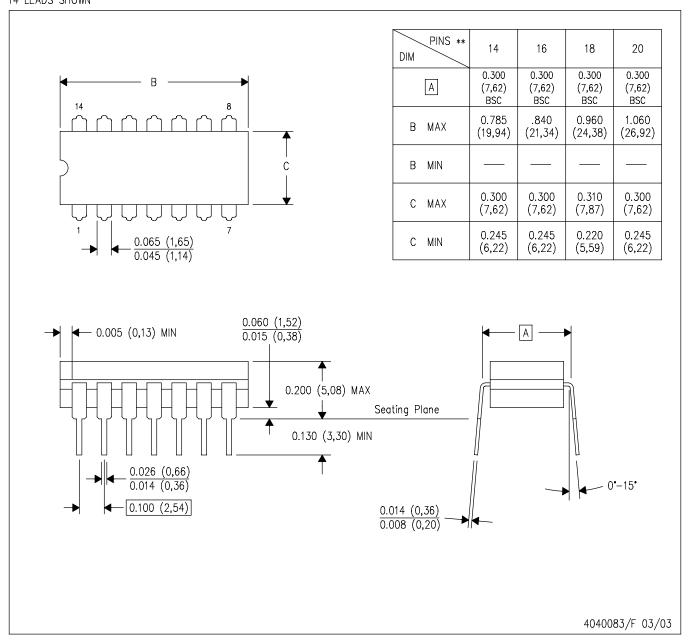
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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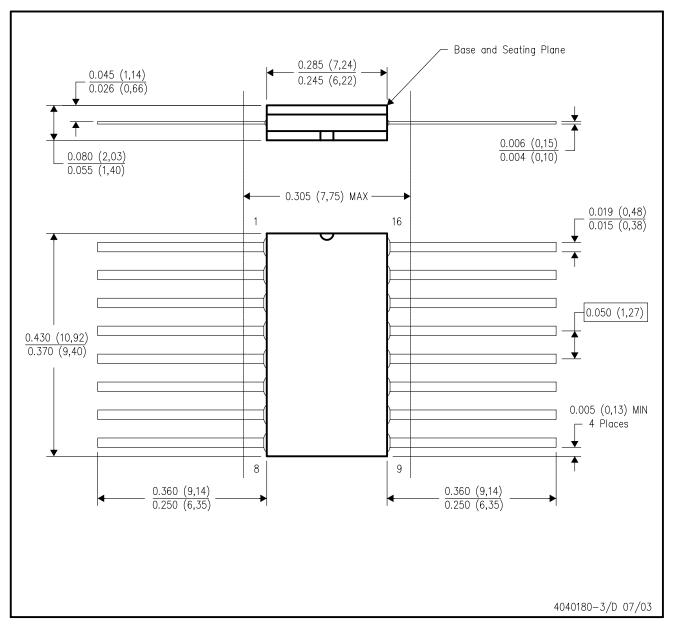
14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



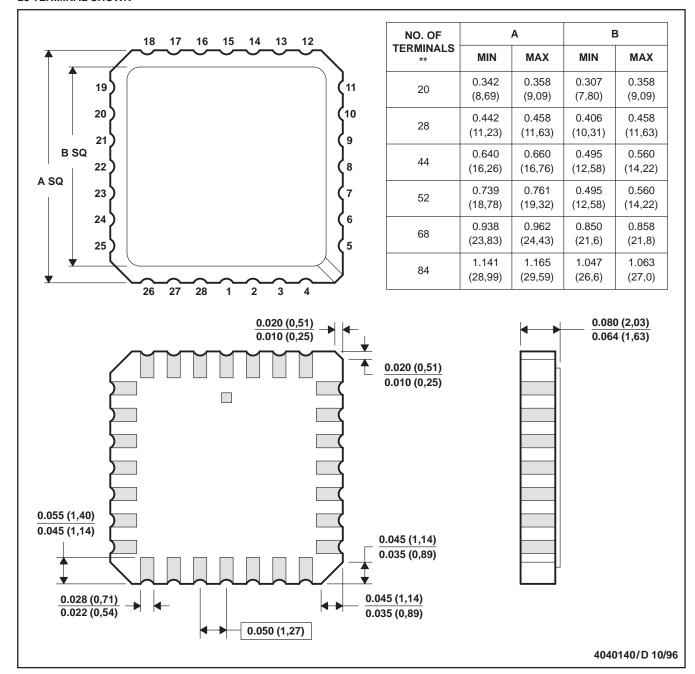
- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



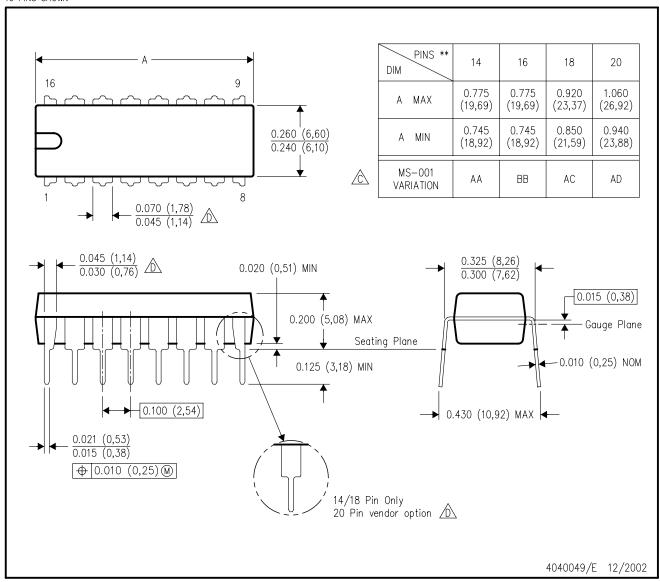
- NOTES: A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

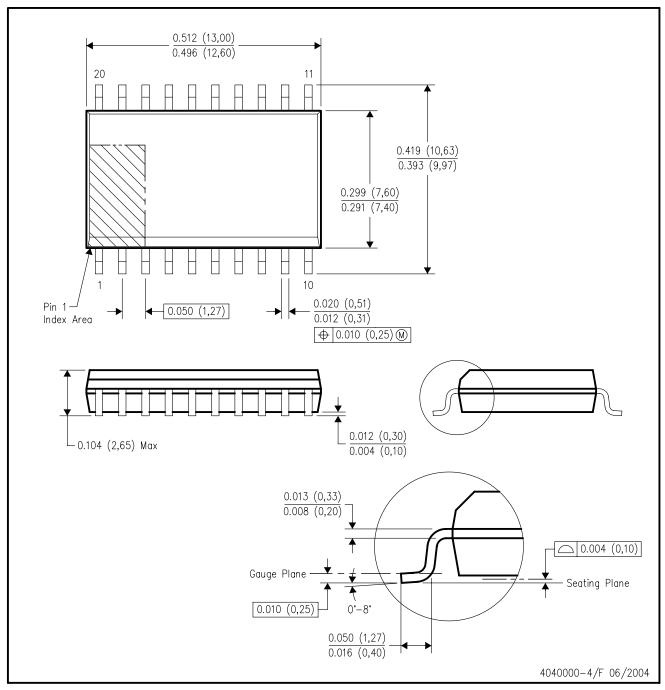
16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.

DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE

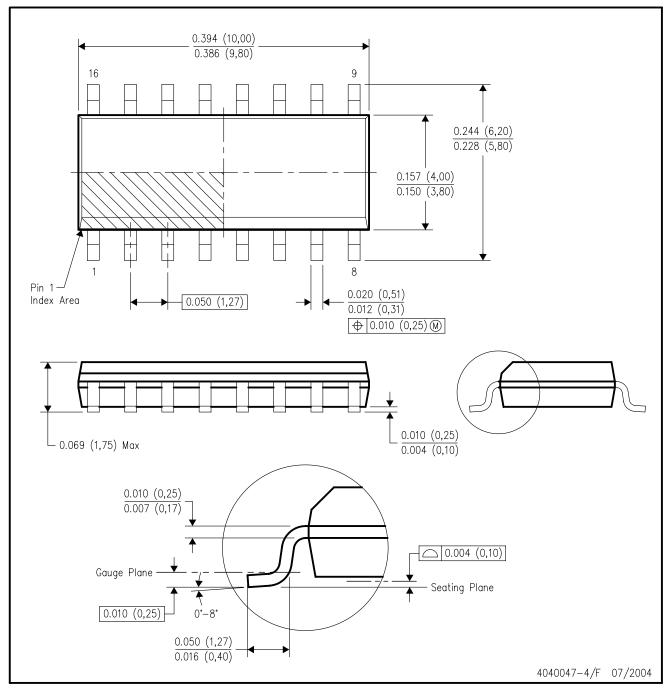


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.

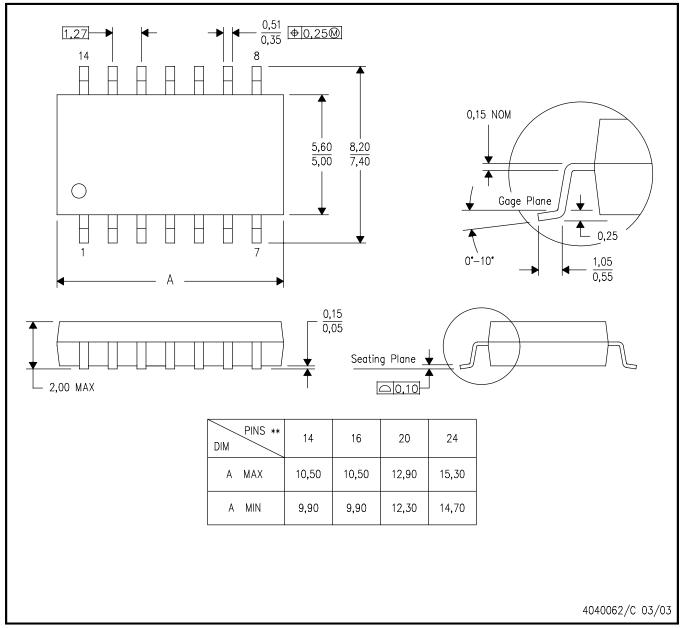


MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- . All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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